

7MHz, 500 μ V Offset, Rail-to-Rail I/O CMOS Operational Amplifier

FEATURES

- HIGH GAIN BANDWIDTH: 7MHz
- RAIL-TO-RAIL INPUT AND OUTPUT
 $\pm 0.5\text{mV}$ Max V_{os}
- INPUT VOLTAGE RANGE: -0.1V to $+5.6\text{V}$
with $V_s = 5.5\text{V}$
- SUPPLY RANGE: $+2.5\text{V}$ to $+5.5\text{V}$
- SHUTDOWN: RS621S/RS622S
- SPECIFIED UP TO $+125^\circ\text{C}$
- *Micro*SIZE PACKAGES: SOT23-5

APPLICATIONS

- SENSORS
- PHOTODIODE AMPLIFICATION
- ACTIVE FILTERS
- TEST EQUIPMENT
- DRIVING A/D CONVERTERS

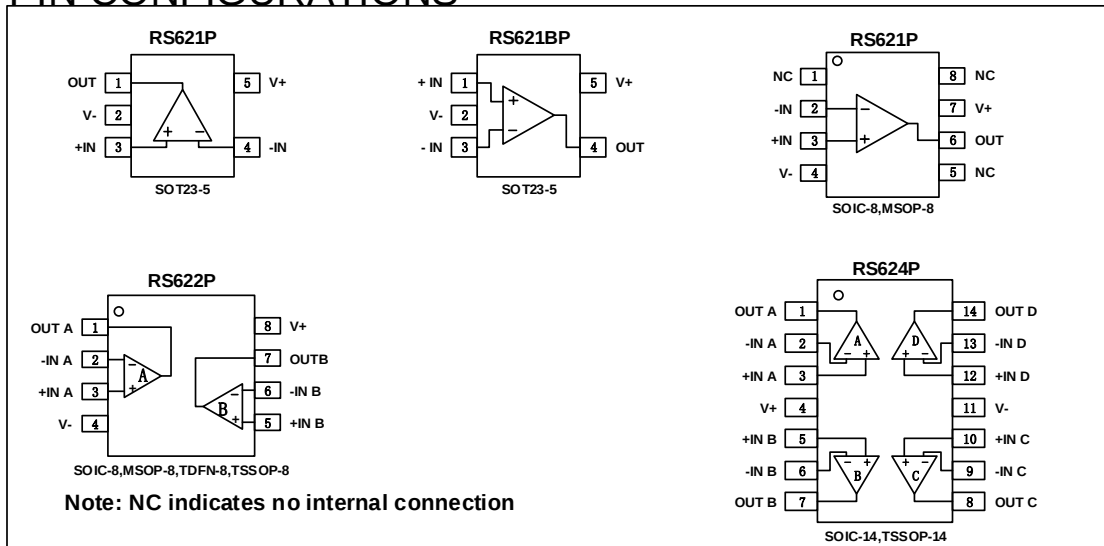
DESCRIPTION

The RS62XP families of products offer low voltage operation and rail-to-rail input and output, as well as excellent speed/power consumption ratio, providing an excellent bandwidth (7MHz) and slew rate of $3.7\text{V}/\mu\text{s}$. The op-amps are unity gain stable and feature an ultra-low input bias current.

The RS621P, RS622P and RS624P has lower offset, which is guaranteed not upper than $\pm 0.5\text{mV}$ at 25°C with $V_s = 5\text{V}$, $V_{cm} = V_s/2$.

The devices are ideal for sensor interfaces, active filters and portable applications. The RS62X families of operational amplifiers are specified at the full temperature range of -40°C to $+125^\circ\text{C}$ under single or dual power supplies of 2.5V to 5.5V .

PIN CONFIGURATIONS



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage, V+ to V-.....	7.0V
Input Terminals, Voltage ⁽²⁾	- 0.5 to (V+) + 0.5V
Current ⁽²⁾	±10mA
Storage Temperature	-65°C to +150°C
Operating Temperature	-40°C to +125°C
Junction Temperature.....	150°C
Package Thermal Resistance @ T _A = +25°C	
SOT23-5, SOT23-6.....	200°C/W
MSOP-8, SOIC-8, TSSOP-8.....	150°C/W
SOIC-14, TSSOP-14.....	100°C/W
Lead Temperature (Soldering, 10s)	260°C
ESD Susceptibility	
HBM	5000V
MM	400V

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.

**ESD SENSITIVITY CAUTION**

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

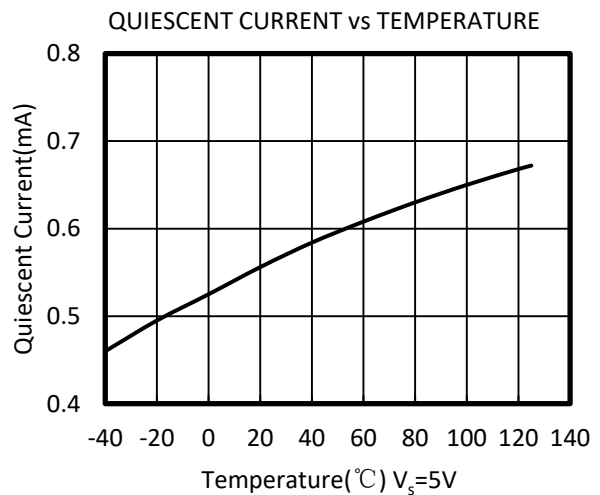
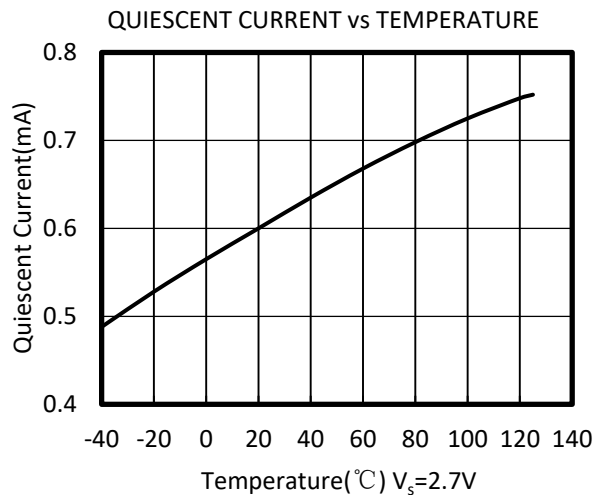
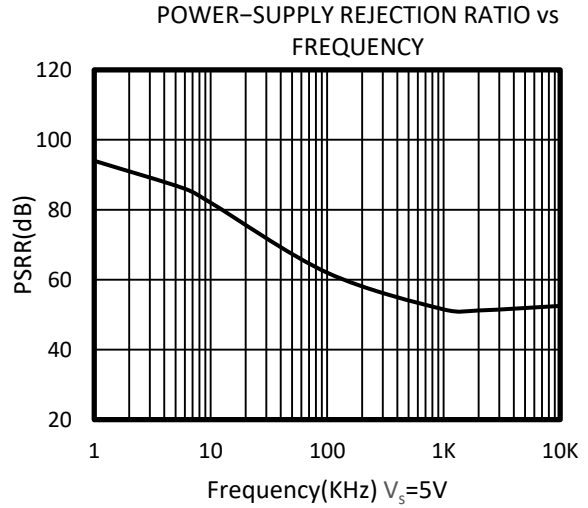
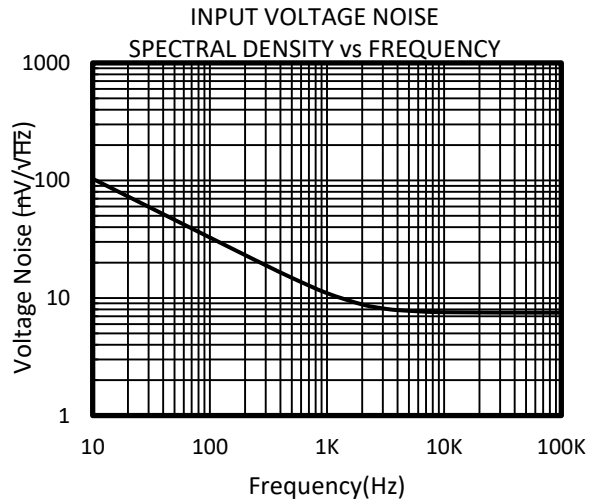
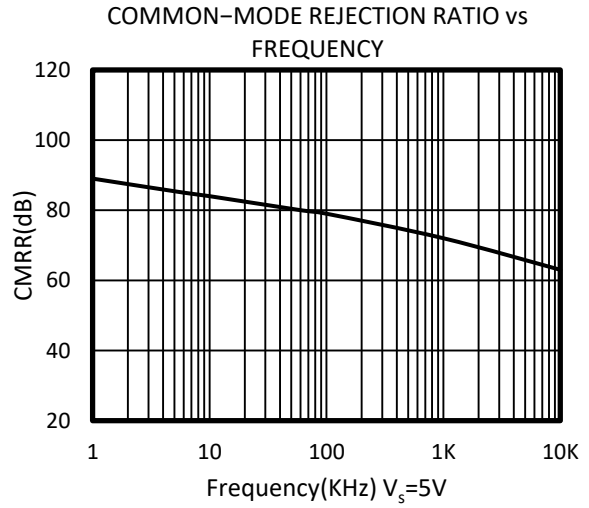
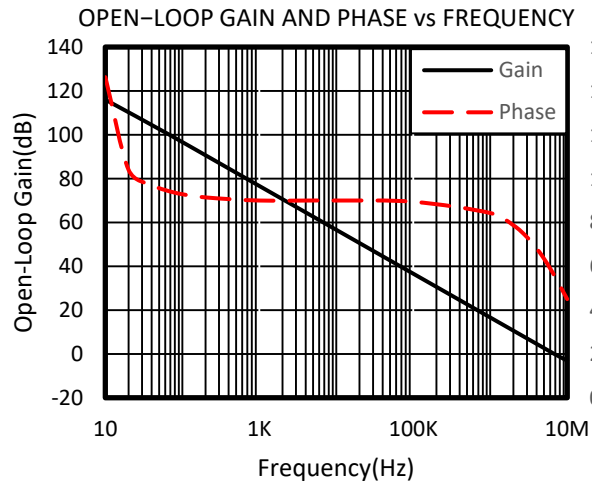
PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING	PACKAGE OPTION
RS621P	RS621P XK	-40°C~125°C	SOIC-8	RS621	Tape and Reel, 2500
	RS621P XF	-40°C~125°C	SOT23-5	621	Tape and Reel, 3000
	RS621B P XF	-40°C~125°C	SOT23-5	621B	Tape and Reel, 3000
	RS621P XM	-40°C~125°C	MSOP-8	RS621	Tape and Reel, 3000
RS622P	RS622P XK	-40°C~125°C	SOIC-8	RS622	Tape and Reel, 2500
	RS622P XM	-40°C~125°C	MSOP-8	RS622	Tape and Reel, 3000
	RS622P XT	-40°C~125°C	TDFN-8	RS622	Tape and Reel, 3000
	RS622P XQ	-40°C~125°C	TSSOP-8	RS622	Tape and Reel, 3000
RS624P	RS624P XP	-40°C~125°C	SOIC -14	RS624	Tape and Reel, 2500
	RS624P XQ	-40°C~125°C	TSSOP-14	RS624	Tape and Reel, 3000

ELECTRICAL CHARACTERISTICS(At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, and $V_{OUT} = V_S/2$, unless otherwise noted.)

PARAMETER		CONDITIONS	T _J	RS621P, RS622P,RS624P			UNIT
				MIN	TYP	MAX	
POWER SUPPLY							
V _S	Operating Voltage Range		25°C	2.5		5.5	V
I _Q	Quiescent Current/Amplifier		25°C		600	800	uA
PSRR	Power-Supply Rejection Ratio	V _S = 2.5V to 5.5V V _{cm} =(V-)+0.5V	25°C	78	93		dB
			-40°C to 125°C	72			
INPUT							
V _{OS}	Input Offset Voltage	V _{cm} =V _S /2	25°C		±0.1	±0.5	mV
V _{OS} TC	Input Offset Voltage Drift	-40°C to 125°C			2		uV/°C
I _B	Input Bias Current		25°C		1	10	pA
I _{OS}	Input Offset Current		25°C		1	10	pA
V _{cm}	Common-Mode Voltage Range	V _S =5.5V	25°C	-0.1		5.6	V
CMRR	Common-Mode Rejection Ratio	V _S = 5.5V, V _{cm} =-0.1V to 4V	25°C	74	92		dB
			-40°C to 125°C	68			
		V _S = 5.5V, V _{cm} = -0.1V to 5.6V	25°C	63	83		
			-40°C to 125°C	60			
OUTPUT							
AOL	Open-Loop Voltage Gain	R _L =2KΩ, V _o = 0.15V to 4.85V	25°C	96	102		dB
			-40°C to 125°C	83			
		R _L = 10kΩ, V _o = 0.05V to 4.95V	25°C	98	106		
			-40°C to 125°C	85			
	Output Swing From Rail	R _L = 2KΩ	25°C		40		mV
		R _L = 10kΩ	25°C		7		
I _{out}	Output Short-Circuit Current		25°C		50		mA
FREQUENCY RESPONSE							
SR	Slew Rate		25°C		3.7		V/us
GBP	Gain-Bandwidth Product		25°C		7		MHz
Φ _m	Phase Margin		25°C		64		°
t _s	Settling Time, 0.1%				0.5		us
	Overload Recovery Time	V _{IN} • Gain ≥ V _S			0.5		us
NOISE							
e _n	Input-Referred Voltage Noise	f = 1 kHz	25°C		11		nV/ √ Hz
		f = 10 kHz	25°C		7.5		nV/ √ Hz

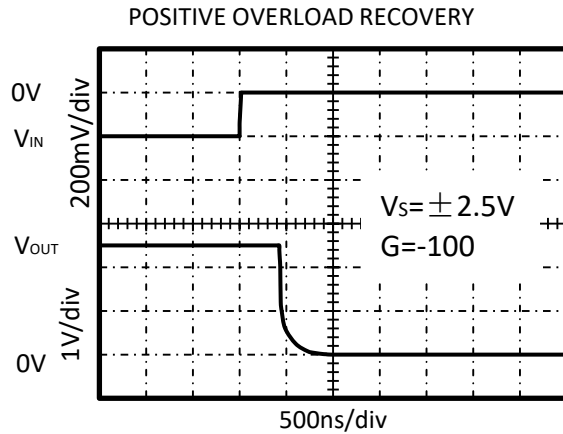
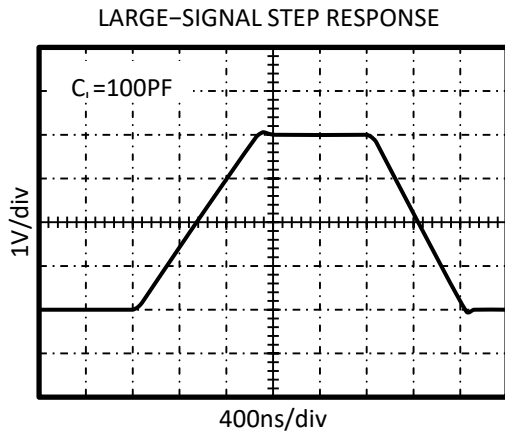
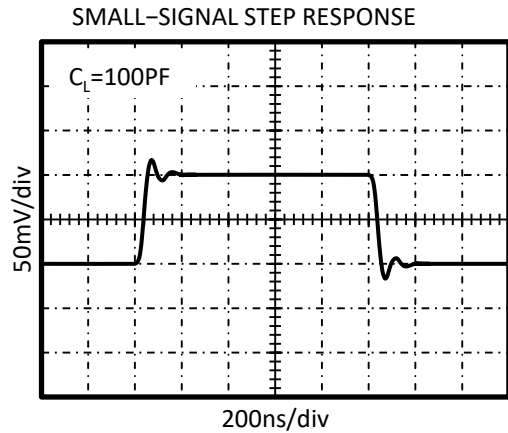
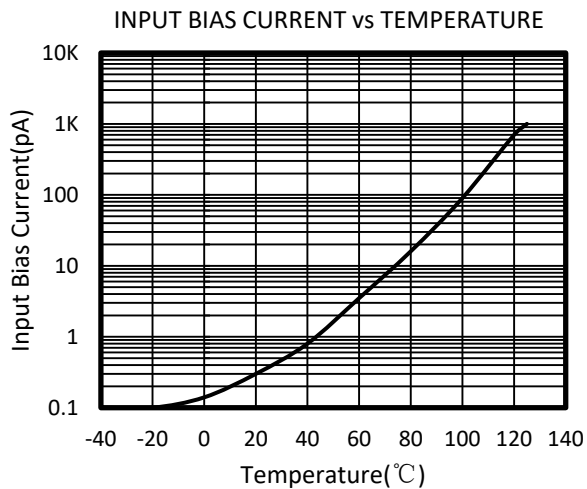
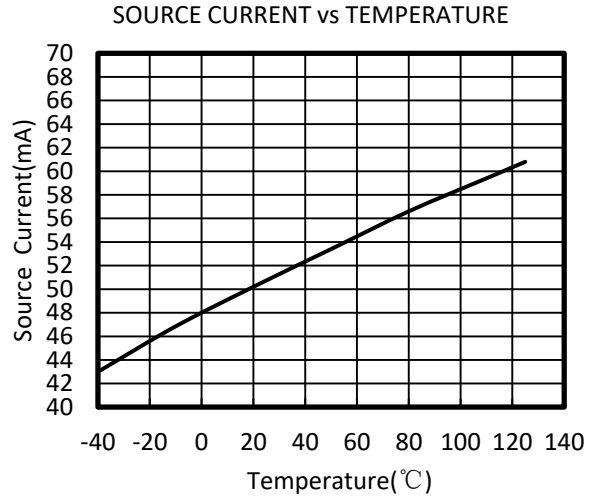
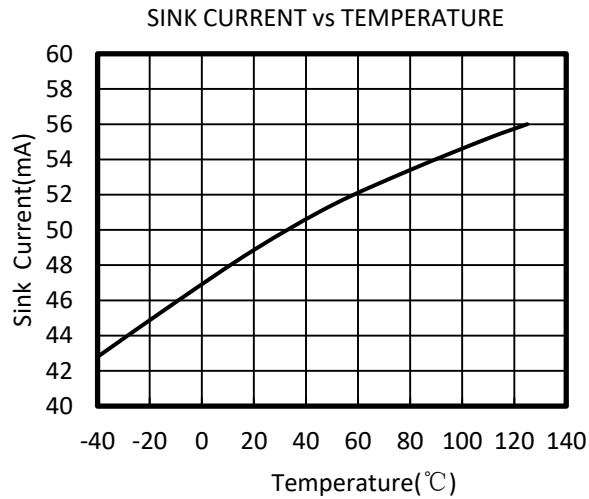
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, unless otherwise noted.



TYPICAL CHARACTERISTICS

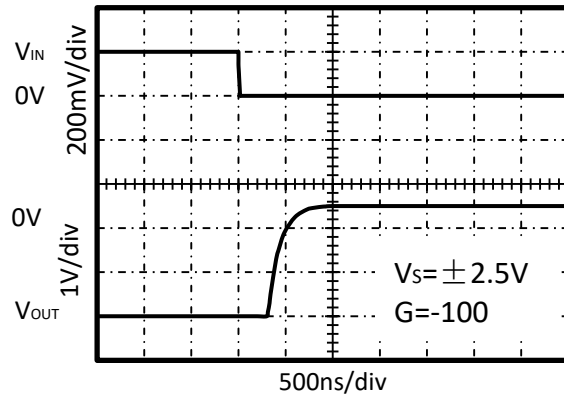
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TYPICAL CHARACTERISTICS

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NEGATIVE OVERLOAD RECOVERY



APPLICATION NOTES

The RS621P, RS622P, RS624P are high precision, rail-to-rail operational amplifiers that can be run from a single-supply voltage 2.5V to 5.5V ($\pm 1.25V$ to $\pm 2.75V$). Supply voltages higher than 7V (absolute maximum) can permanently damage the amplifier.

Rail-to-rail input and output swing significantly increases dynamic range, especially in low-supply applications.

Good layout practice mandates use of a 0.1uF capacitor placed closely across the supply pins.

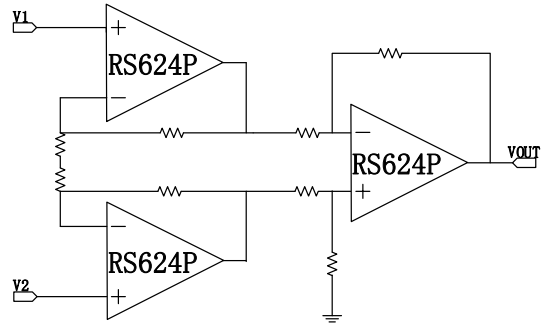


Figure2. Amplifier instrumentation amplifier

LAYOUT GUIDELINS

Attention to good layout practices is always recommended. Keep traces short. When possible, use a PCB ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1uF capacitor closely across the supply pins.

These guidelines should be applied throughout the analog circuit to improve performance and provide benefits such as reducing the EMI susceptibility.

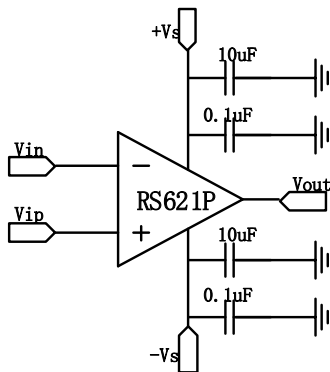


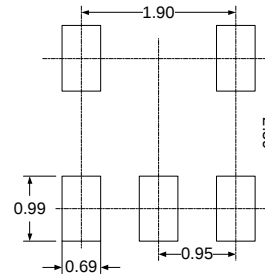
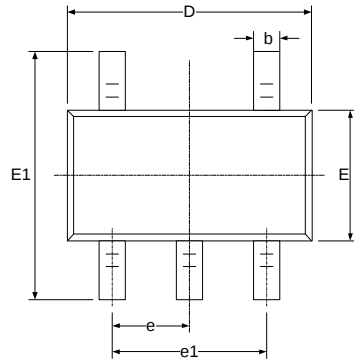
Figure1. Amplifier with Bypass Capacitors

INSTRUMENTATION AMPLIFIER

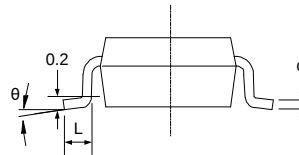
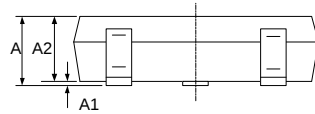
In the three-op amp, instrumentation amplifier configuration shown in Figure2,

PACKAGE OUTLINE DIMENSIONS

SOT23-5

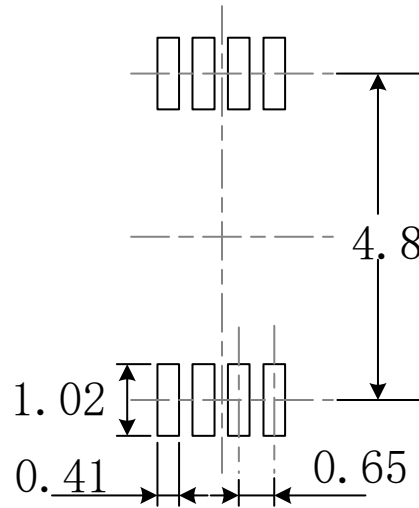
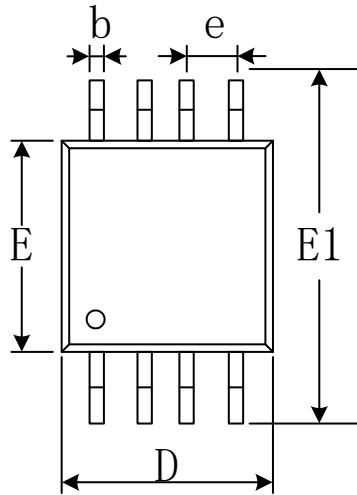


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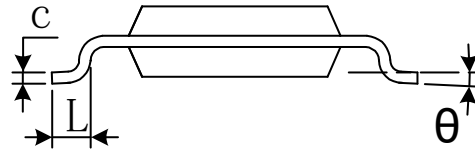
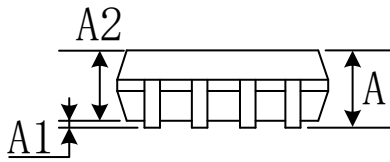


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

MSOP-8

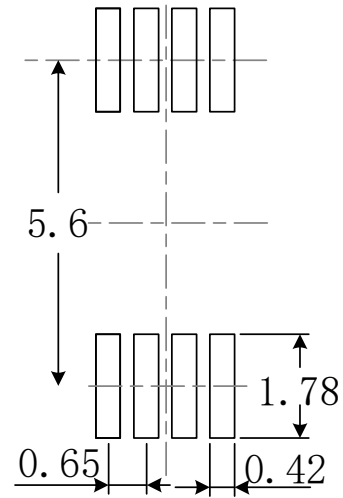
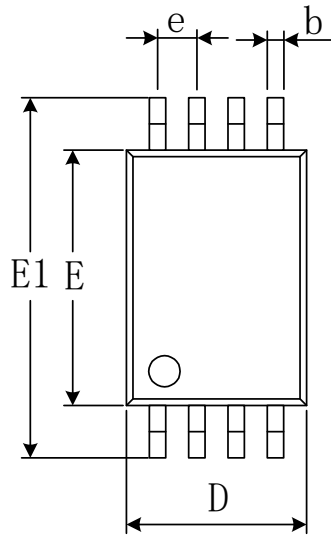


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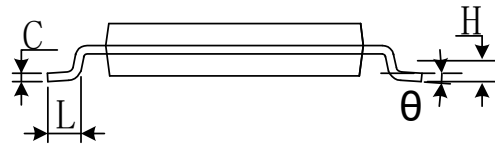
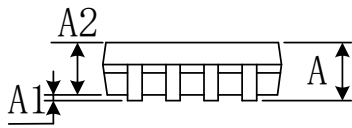


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
e	0.650(BSC)		0.026(BSC)	
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

TSSOP-8

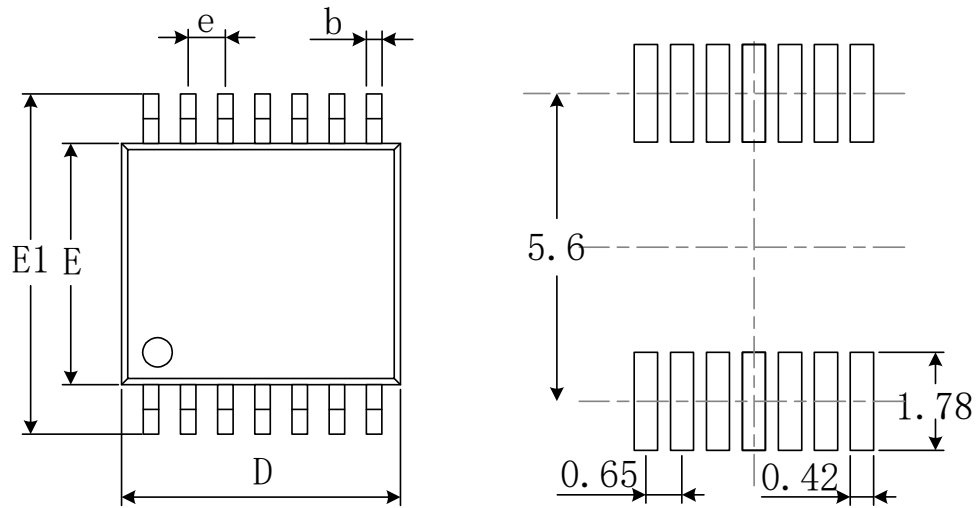


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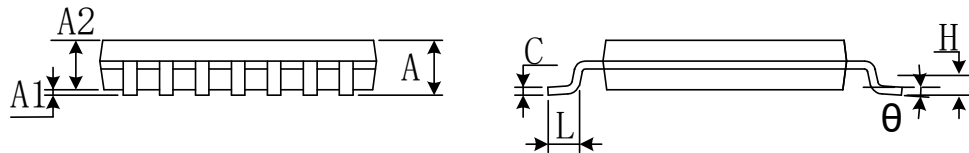


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D	2.900	3.100	0.114	0.122
E	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650(BSC)		0.026(BSC)	
L	0.500	0.700	0.020	0.028
H	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°

TSSOP-14

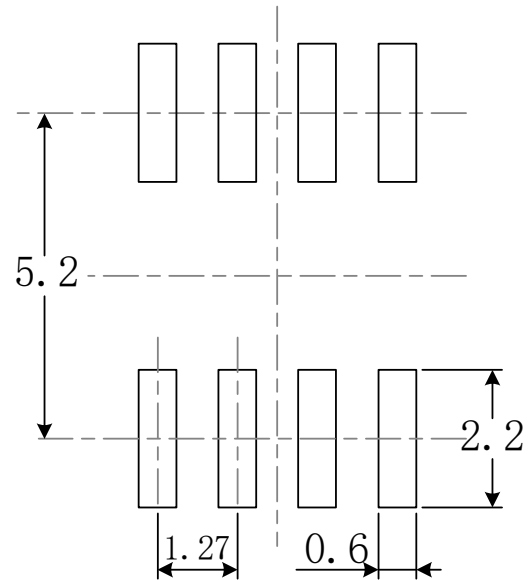
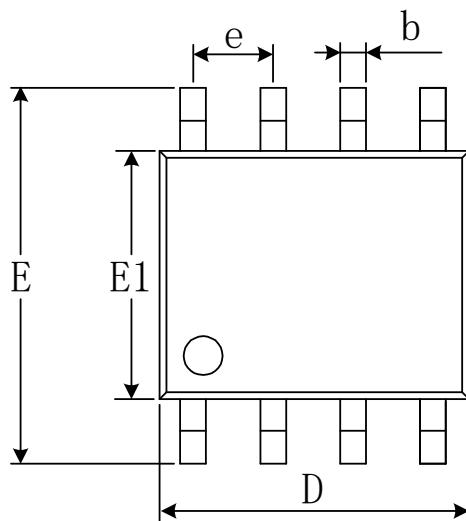


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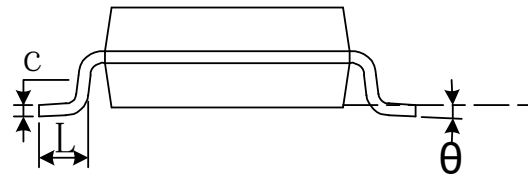
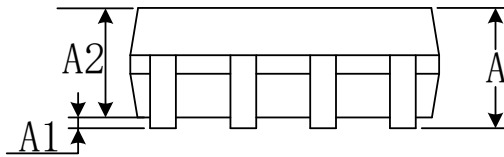


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A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D	4.860	5.100	0.191	0.201
E	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650(BSC)		0.026(BSC)	
L	0.500	0.700	0.020	0.028
H	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°

SOIC-8

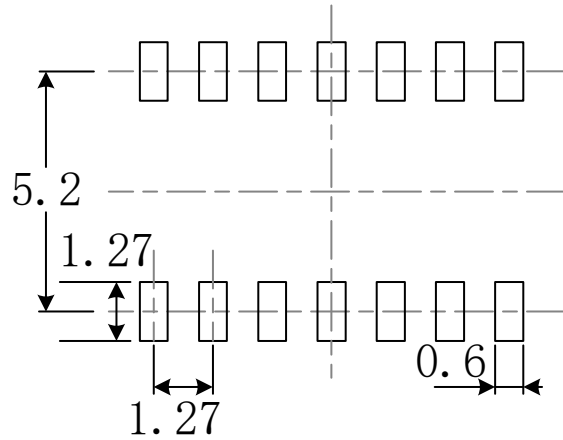
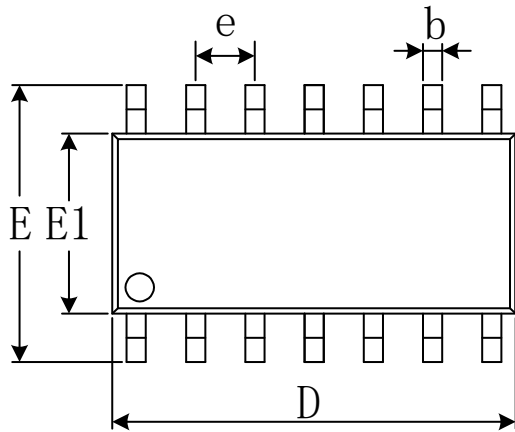


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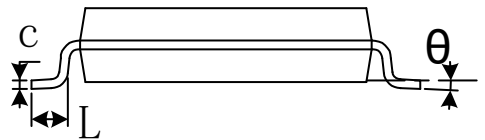
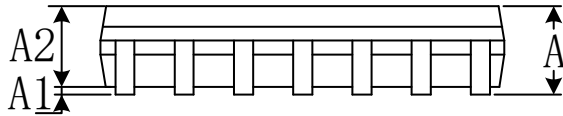


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270(BSC)		0.050(BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

SOIC-14

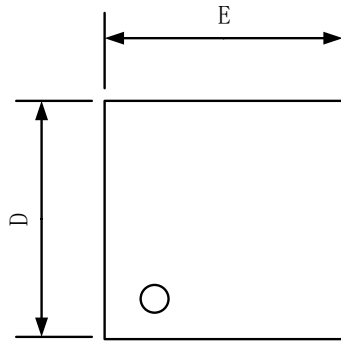


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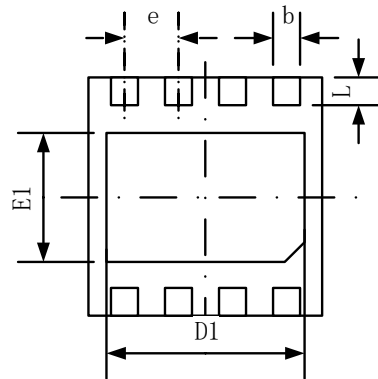


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D	8.450	8.850	0.333	0.348
e	1.270(BSC)		0.050(BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

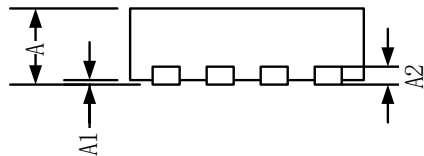
TDFN-3x3-8L



TOP VIEW



BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203		0.008	
b	0.300	0.400	0.012	0.016
D	2.900	3.100	0.114	0.122
D1	2.510	2.610	0.099	0.103
E	2.900	3.100	0.114	0.122
E1	1.550	1.650	0.061	0.065
e	0.650 TYP		0.026 TYP	
L	0.350	0.450	0.014	0.018